

■ Features

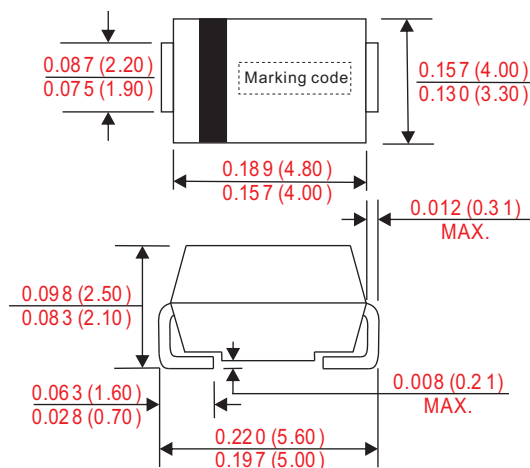
- Electrostatic discharge (ESD) test under IEC6100-4-2 standard >16KV(SK32B~SK36B).
standard >10KV(SK310B~SK320B).
- Low profile surface mounted application in order to optimize board space.
- Low power loss, high efficiency.
- High current capability, low forward voltage drop.
- Ultra high-speed switching.
- Silicon epitaxial planar chip, metal silicon junction.
- Suffix "G" indicates Halogen-free part, ex.SK32BG.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228

■ Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AA / SMB
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Weight : 0.003 ounce, 0.091 gram

■ Outline

SMB(DO-214AA)



Dimensions in inches and (millimeters)

■ Maximum ratings and electrical characteristics

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Parameter	Conditions	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I_O			3.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC method)	I_{FSM}			70	A
Reverse current	$V_R = V_{RRM} \quad T_A = 25^\circ\text{C}$	I_R			0.5	mA
	$V_R = V_{RRM} \quad T_A = 100^\circ\text{C}$				20	
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		250		pF
Thermal resistance	Junction to ambient	$R_{\theta JA}$		55		°C/W
Storage temperature		T_{STG}	-55		+175	°C

Symbol	Marking code	Max. repetitive peak reverse voltage V_{RRM} (V)	Max. RMS voltage V_{RMS} (V)	Max. DC blocking voltage V_R (V)	Max. forward voltage @3A, $T_A = 25^\circ\text{C}$ V_F (V)	Operating temperature T_J (°C)
SK32B	SK32	20	14	20	0.45	-50 ~ +150
SK34B	SK34	40	28	40	0.50	
SK36B	SK36	60	42	60	0.70	
SK310B	SK310	100	70	100	0.81	
SK315B	SK315	150	105	150	0.87	-50 ~ +175
SK320B	SK320	200	140	200	0.90	

■ Rating and characteristic curves

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

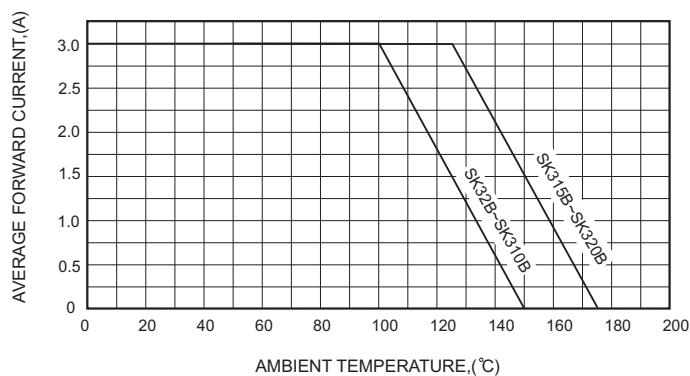


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

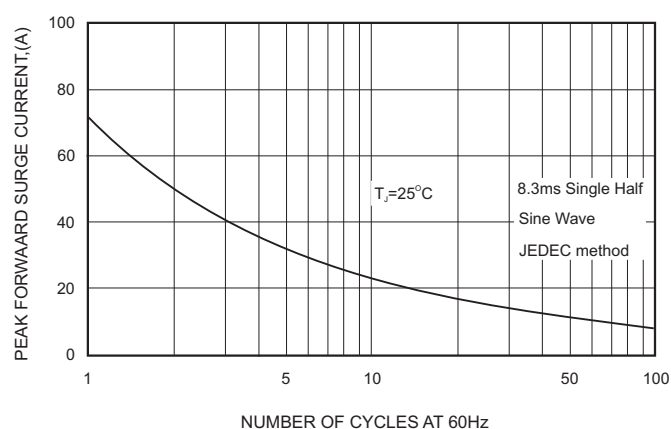


FIG.4-TYPICAL JUNCTION CAPACITANCE

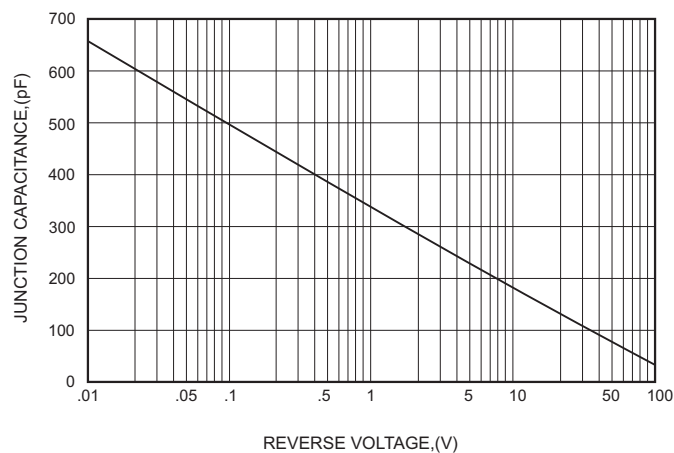


FIG.2-TYPICAL FORWARD CHARACTERISTICS

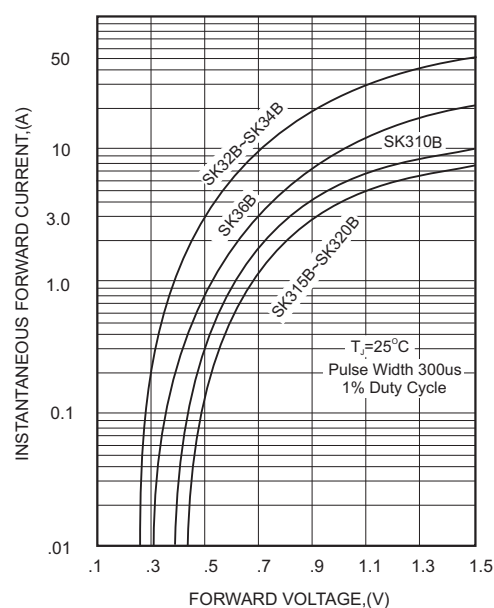
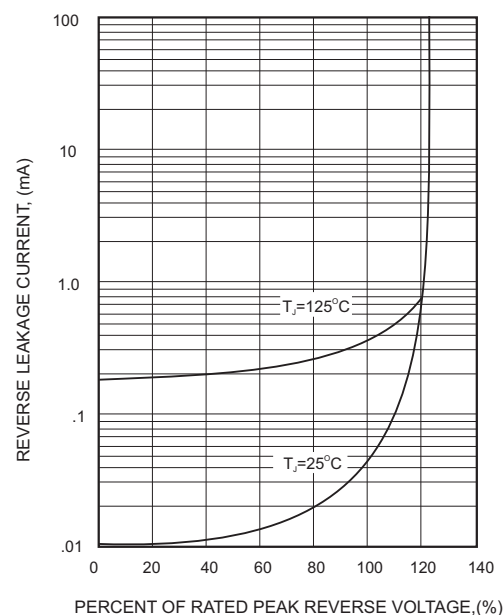
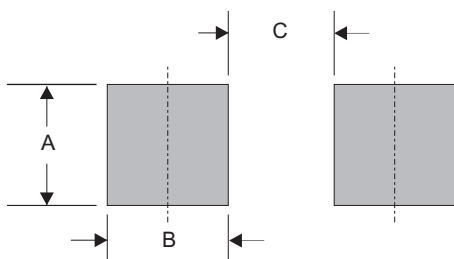


FIG.5 - TYPICAL REVERSE CHARACTERISTICS



■ SMB foot print



A	B	C
0.091 (2.30)	0.098 (2.50)	0.071 (1.80)

Dimensions in inches and (millimeters)

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